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# HM628512B Series

4 M SRAM (512-kword  $\times$  8-bit)

# HITACHI

ADE-203-903D (Z)

Rev. 3.0

Aug. 24, 1999

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## Description

The Hitachi HM628512B is a 4-Mbit static RAM organized 512-kword  $\times$  8-bit. It realizes higher density, higher performance and low power consumption by employing 0.35  $\mu$ m Hi-CMOS process technology. The device, packaged in a 525-mil SOP (foot print pitch width) or 400-mil TSOP TYPE II or 600-mil plastic DIP, is available for high density mounting. The HM628512B is suitable for battery backup system.

## Features

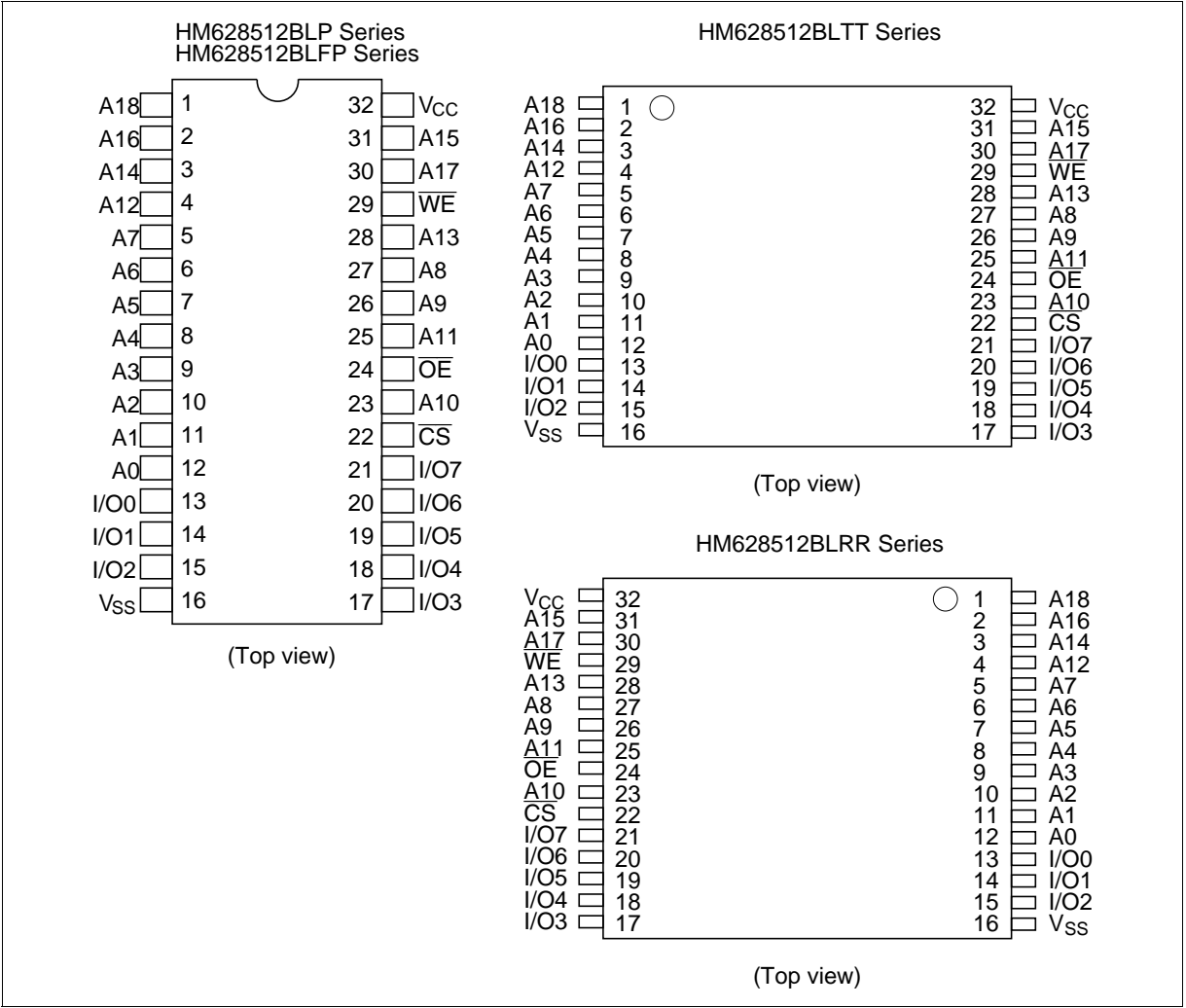
- Single 5 V supply
- Access time: 55/70 ns (max)
- Power dissipation
  - Active: 50 mW/MHz (typ)
  - Standby: 10  $\mu$ W (typ)
- Completely static memory. No clock or timing strobe required
- Equal access and cycle times
- Common data input and output: Three state output
- Directly TTL compatible: All inputs and outputs
- Battery backup operation

# HM628512B Series

## Ordering Information

Type No.	Access time	Package
HM628512BLP-5	55 ns	600-mil 32-pin plastic DIP (DP-32)
HM628512BLP-7	70 ns	
HM628512BLP-5SL	55 ns	
HM628512BLP-7SL	70 ns	
HM628512BLP-5UL	55 ns	
HM628512BLP-7UL	70 ns	
HM628512BLFP-5	55 ns	525-mil 32-pin plastic SOP (FP-32D)
HM628512BLFP-7	70 ns	
HM628512BLFP-5SL	55 ns	
HM628512BLFP-7SL	70 ns	
HM628512BLFP-5UL	55 ns	
HM628512BLFP-7UL	70 ns	
HM628512BLTT-5	55 ns	400-mil 32-pin plastic TSOP II (TTP-32D)
HM628512BLTT-7	70 ns	
HM628512BLTT-5SL	55 ns	
HM628512BLTT-7SL	70 ns	
HM628512BLTT-5UL	55 ns	
HM628512BLTT-7UL	70 ns	
HM628512BLRR-5	55 ns	400-mil 32-pin plastic TSOP II reverse (TTP-32DR)
HM628512BLRR-7	70 ns	
HM628512BLRR-5SL	55 ns	
HM628512BLRR-7SL	70 ns	
HM628512BLRR-5UL	55 ns	
HM628512BLRR-7UL	70 ns	

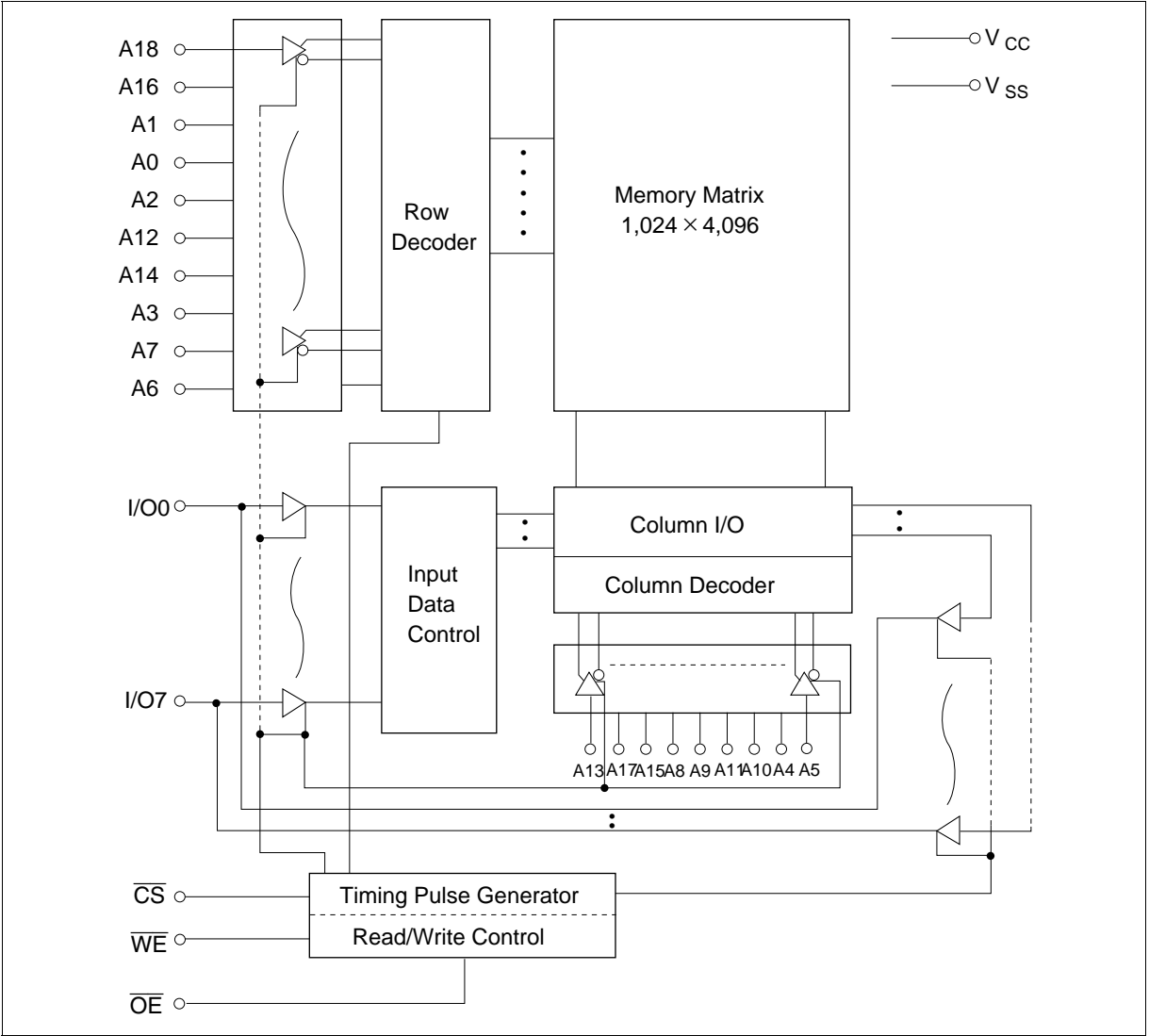
Pin Arrangement



Pin Description

Pin name	Function
A0 to A18	Address input
I/O0 to I/O7	Data input/output
CS	Chip select
OE	Output enable
WE	Write enable
V <sub>CC</sub>	Power supply
V <sub>SS</sub>	Ground

Block Diagram



## Function Table

$\overline{\text{WE}}$	$\overline{\text{CS}}$	$\overline{\text{OE}}$	Mode	$V_{\text{CC}}$ current	Dout pin	Ref. cycle
×	H	×	Not selected	$I_{\text{SB}}, I_{\text{SB1}}$	High-Z	—
H	L	H	Output disable	$I_{\text{CC}}$	High-Z	—
H	L	L	Read	$I_{\text{CC}}$	Dout	Read cycle
L	L	H	Write	$I_{\text{CC}}$	Din	Write cycle (1)
L	L	L	Write	$I_{\text{CC}}$	Din	Write cycle (2)

Note: ×: H or L

## Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Power supply voltage	$V_{\text{CC}}$	−0.5 to +7.0	V
Voltage on any pin relative to $V_{\text{SS}}$	$V_{\text{T}}$	−0.5* <sup>1</sup> to $V_{\text{CC}} + 0.3$ * <sup>2</sup>	V
Power dissipation	$P_{\text{T}}$	1.0	W
Operating temperature	$T_{\text{opr}}$	−20 to +70	°C
Storage temperature	$T_{\text{stg}}$	−55 to +125	°C
Storage temperature under bias	$T_{\text{bias}}$	−20 to +85	°C

Notes: 1. −3.0 V for pulse half-width ≤ 30 ns

2. Maximum voltage is 7.0 V

Recommended DC Operating Conditions ( $T_{\text{a}} = -20$  to +70°C)

Parameter	Symbol	Min	Typ	Max	Unit
Supply voltage	$V_{\text{CC}}$	4.5	5.0	5.5	V
	$V_{\text{SS}}$	0	0	0	V
Input high voltage	$V_{\text{IH}}$	2.2	—	$V_{\text{CC}} + 0.3$	V
Input low voltage	$V_{\text{IL}}$	−0.3* <sup>1</sup>	—	0.8	V

Note: 1. −3.0 V for pulse half-width ≤ 30 ns

## DC Characteristics (Ta = -20 to +70°C, V<sub>CC</sub> = 5 V ±10% , V<sub>SS</sub> = 0 V)

Parameter	Symbol	Min	Typ* <sup>1</sup>	Max	Unit	Test conditions
Input leakage current	I <sub>LI</sub>	—	—	1	μA	V <sub>in</sub> = V <sub>SS</sub> to V <sub>CC</sub>
Output leakage current	I <sub>LO</sub>	—	—	1	μA	$\overline{CS} = V_{IH}$ or $\overline{OE} = V_{IH}$ or $\overline{WE} = V_{IL}$ , V <sub>I/O</sub> = V <sub>SS</sub> to V <sub>CC</sub>
Operating power supply current: DC	I <sub>CC</sub>	—	8	15	mA	$\overline{CS} = V_{IL}$ , others = V <sub>IH</sub> /V <sub>IL</sub> , I <sub>I/O</sub> = 0 mA
Operating power supply current	I <sub>CC1</sub>	—	40	60	mA	Min cycle, duty = 100% $\overline{CS} = V_{IL}$ , others = V <sub>IH</sub> /V <sub>IL</sub> I <sub>I/O</sub> = 0 mA
Operating power supply current	I <sub>CC2</sub>	—	10	20	mA	Cycle time = 1 μs, duty = 100% I <sub>I/O</sub> = 0 mA, $\overline{CS} \leq 0.2$ V V <sub>IH</sub> ≥ V <sub>CC</sub> - 0.2 V, V <sub>IL</sub> ≤ 0.2 V
Standby power supply current: DC	I <sub>SB</sub>	—	1	3	mA	$\overline{CS} = V_{IH}$
Standby power supply current (1): DC	I <sub>SB1</sub>	—	2* <sup>2</sup>	100* <sup>2</sup>	μA	V <sub>in</sub> ≥ 0 V, $\overline{CS} \geq V_{CC} - 0.2$ V
		—	2* <sup>3</sup>	50* <sup>3</sup>	μA	
		—	2* <sup>4</sup>	20* <sup>4</sup>	μA	
		—	—	—	—	
Output low voltage	V <sub>OL</sub>	—	—	0.4	V	I <sub>OL</sub> = 2.1 mA
Output high voltage	V <sub>OH</sub>	2.4	—	—	V	I <sub>OH</sub> = -1.0 mA

- Notes: 1. Typical values are at V<sub>CC</sub> = 5.0 V, Ta = +25°C and specified loading, and not guaranteed.  
2. This characteristics is guaranteed only for L version.  
3. This characteristics is guaranteed only for L-SL version.  
4. This characteristics is guaranteed only for L-UL version.

## Capacitance (Ta = +25°C, f = 1 MHz)

Parameter	Symbol	Typ	Max	Unit	Test conditions
Input capacitance* <sup>1</sup>	C <sub>in</sub>	—	8	pF	V <sub>in</sub> = 0 V
Input/output capacitance* <sup>1</sup>	C <sub>I/O</sub>	—	10	pF	V <sub>I/O</sub> = 0 V

- Note: 1. This parameter is sampled and not 100% tested.

**AC Characteristics** ( $T_a = -20$  to  $+70^\circ\text{C}$ ,  $V_{CC} = 5\text{ V} \pm 10\%$ , unless otherwise noted.)

### Test Conditions

- Input pulse levels: 0.8 V to 2.4 V
- Input rise and fall time: 5 ns
- Input and output timing reference levels: 1.5 V
- Output load: 1 TTL Gate +  $C_L$  (100 pF) (HM628512B-7)  
1 TTL Gate +  $C_L$  (50 pF) (HM628512B-5)  
(Including scope & jig)

### Read Cycle

		HM628512B					
		-5		-7			
Parameter	Symbol	Min	Max	Min	Max	Unit	Notes
Read cycle time	t <sub>RC</sub>	55	—	70	—	ns	
Address access time	t <sub>AA</sub>	—	55	—	70	ns	
Chip select access time	t <sub>CO</sub>	—	55	—	70	ns	
Output enable to output valid	t <sub>OE</sub>	—	25	—	35	ns	
Chip selection to output in low-Z	t <sub>LZ</sub>	10	—	10	—	ns	2
Output enable to output in low-Z	t <sub>OLZ</sub>	5	—	5	—	ns	2
Chip deselection to output in high-Z	t <sub>HZ</sub>	0	20	0	25	ns	1, 2
Output disable to output in high-Z	t <sub>OHZ</sub>	0	20	0	25	ns	1, 2
Output hold from address change	t <sub>OH</sub>	10	—	10	—	ns	

## Write Cycle

		HM628512B					
		-5		-7			
Parameter	Symbol	Min	Max	Min	Max	Unit	Notes
Write cycle time	t <sub>WC</sub>	55	—	70	—	ns	
Chip selection to end of write	t <sub>CW</sub>	50	—	60	—	ns	4
Address setup time	t <sub>AS</sub>	0	—	0	—	ns	5
Address valid to end of write	t <sub>AW</sub>	50	—	60	—	ns	
Write pulse width	t <sub>WP</sub>	40	—	50	—	ns	3, 12
Write recovery time	t <sub>WR</sub>	0	—	0	—	ns	6
$\overline{WE}$ to output in high-Z	t <sub>WHZ</sub>	0	20	0	25	ns	1, 2, 7
Data to write time overlap	t <sub>DW</sub>	25	—	30	—	ns	
Data hold from write time	t <sub>DH</sub>	0	—	0	—	ns	
Output active from output in high-Z	t <sub>OW</sub>	5	—	5	—	ns	2
Output disable to output in high-Z	t <sub>OHZ</sub>	0	20	0	25	ns	1, 2, 7

Notes: 1.  $t_{HZ}$ ,  $t_{OHZ}$  and  $t_{WHZ}$  are defined as the time at which the outputs achieve the open circuit conditions and are not referred to output voltage levels.

2. This parameter is sampled and not 100% tested.

3. A write occurs during the overlap ( $t_{WP}$ ) of a low  $\overline{CS}$  and a low  $\overline{WE}$ . A write begins at the later transition of  $\overline{CS}$  going low or  $\overline{WE}$  going low. A write ends at the earlier transition of  $\overline{CS}$  going high or  $\overline{WE}$  going high.  $t_{WP}$  is measured from the beginning of write to the end of write.

4.  $t_{CW}$  is measured from  $\overline{CS}$  going low to the end of write.

5.  $t_{AS}$  is measured from the address valid to the beginning of write.

6.  $t_{WR}$  is measured from the earlier of  $\overline{WE}$  or  $\overline{CS}$  going high to the end of write cycle.

7. During this period, I/O pins are in the output state so that the input signals of the opposite phase to the outputs must not be applied.

8. If the  $\overline{CS}$  low transition occurs simultaneously with the  $\overline{WE}$  low transition or after the  $\overline{WE}$  transition, the output remain in a high impedance state.

9. Dout is the same phase of the write data of this write cycle.

10. Dout is the read data of next address.

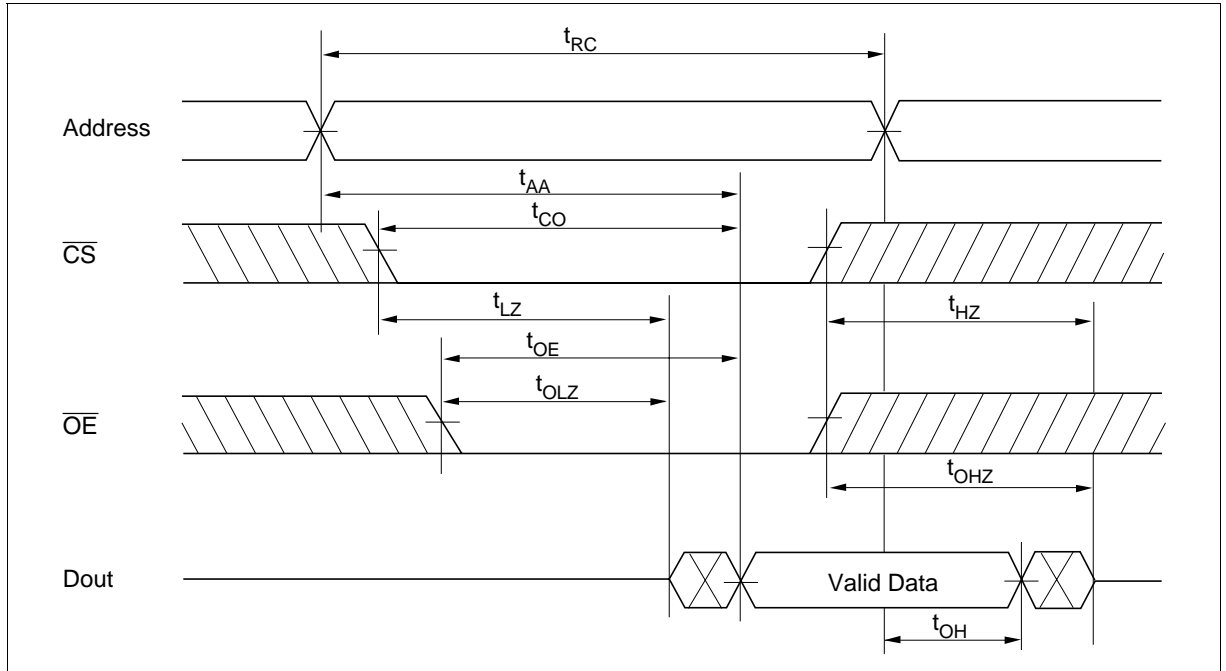
11. If  $\overline{CS}$  is low during this period, I/O pins are in the output state. Therefore, the input signals of the opposite phase to the outputs must not be applied to them.

12. In the write cycle with  $\overline{OE}$  low fixed,  $t_{WP}$  must satisfy the following equation to avoid a problem of data bus contention.  $t_{WP} \geq t_{DW} \text{ min} + t_{WHZ} \text{ max}$

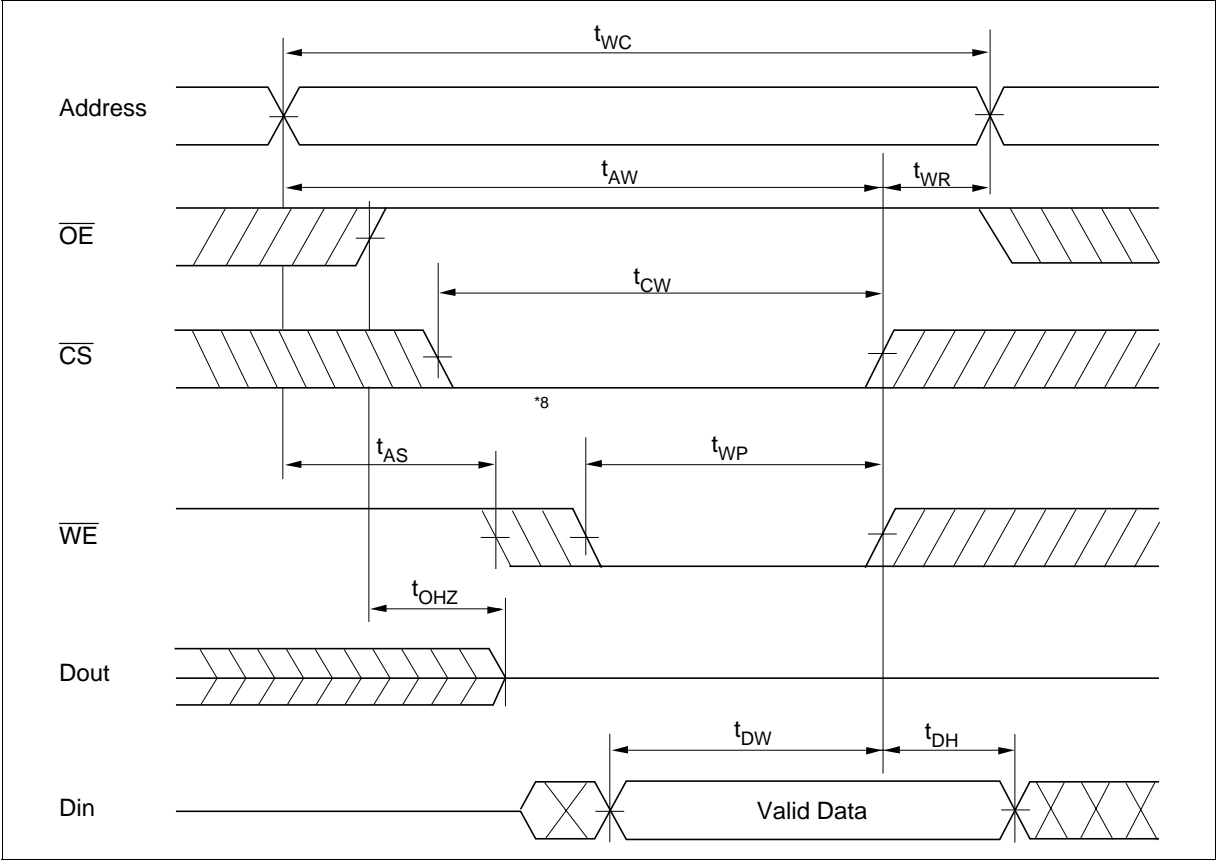


## Timing Waveforms

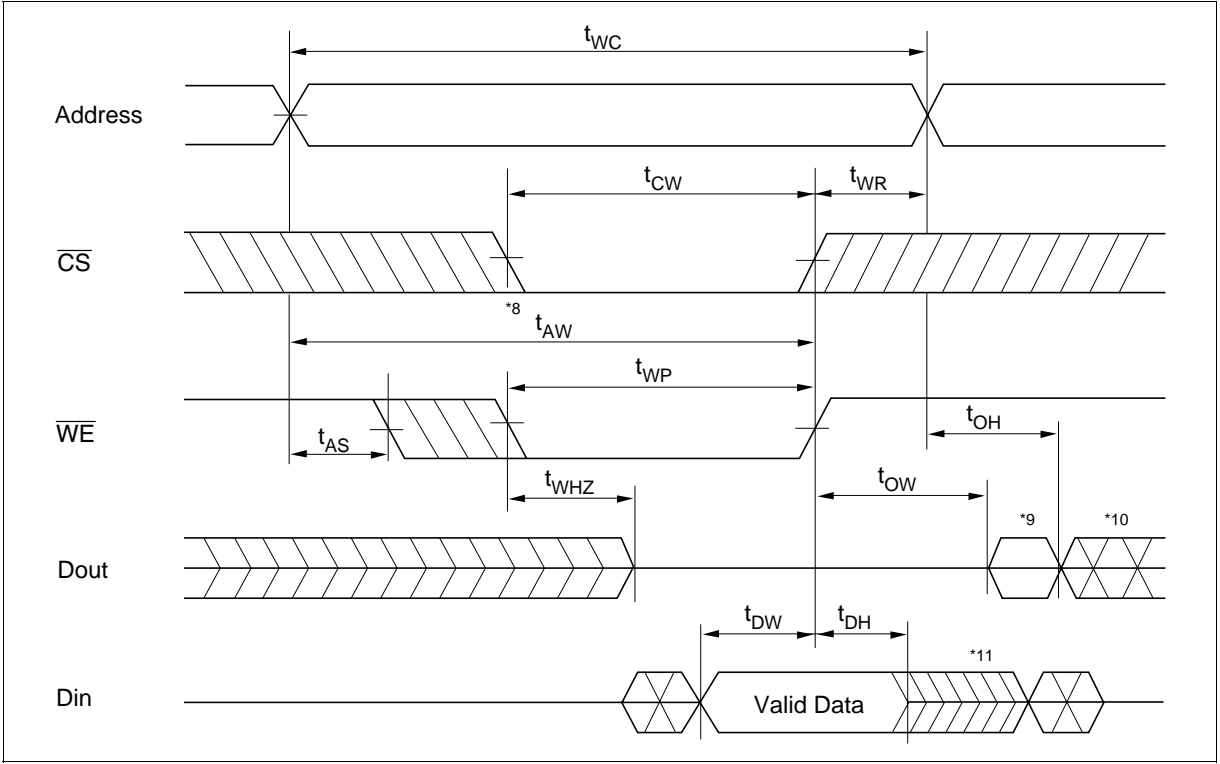
### Read Timing Waveform ( $\overline{WE} = V_{IH}$ )



Write Timing Waveform (1) ( $\overline{\text{OE}}$  Clock)



Write Timing Waveform (2) ( $\overline{\text{OE}}$  Low Fixed)

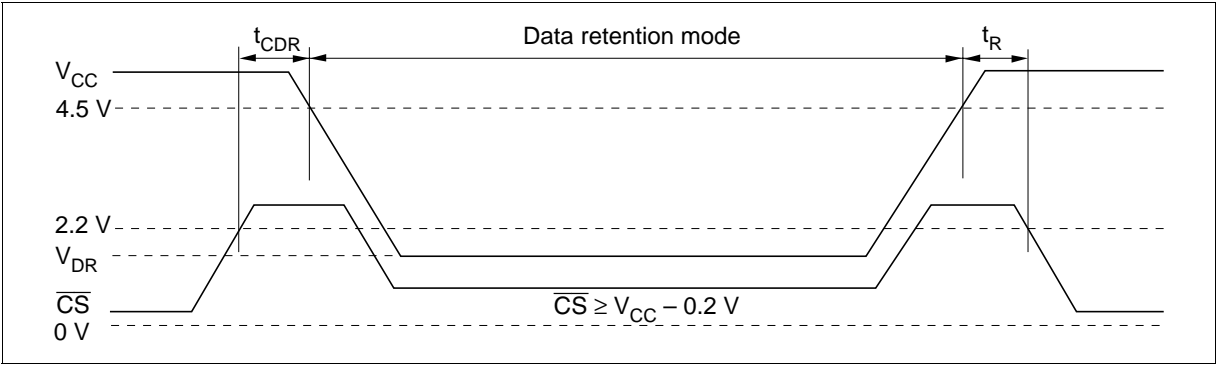


Low V<sub>CC</sub> Data Retention Characteristics (Ta = -20 to +70°C)

Parameter	Symbol	Min	Typ	Max	Unit	Test conditions**
V <sub>CC</sub> for data retention	V <sub>DR</sub>	2	—	—	V	$\overline{CS} \geq V_{CC} - 0.2\text{ V}$ , Vin ≥ 0 V
Data retention current	I <sub>CCDR</sub>	—	1* <sup>5</sup>	50* <sup>1</sup>	μA	$V_{CC} = 3.0\text{ V}$ , Vin ≥ 0 V $\overline{CS} \geq V_{CC} - 0.2\text{ V}$
		—	1* <sup>5</sup>	15* <sup>2</sup>	μA	
		—	1* <sup>5</sup>	10* <sup>3</sup>	μA	
Chip deselect to data retention time	t <sub>CDR</sub>	0	—	—	ns	See retention waveform
Operation recovery time	t <sub>R</sub>	t <sub>RC</sub> * <sup>6</sup>	—	—	ns	

- Notes:
- 1. For L-version and 20 μA (max.) at Ta = -20 to +40°C.
  - 2. For L-SL-version and 3 μA (max.) at Ta = -20 to +40°C.
  - 3. For L-UL-version and 3 μA (max.) at Ta = -20 to +40°C.
  - 4.  $\overline{CS}$  controls address buffer,  $\overline{WE}$  buffer,  $\overline{OE}$  buffer, and Din buffer. In data retention mode, Vin levels (address,  $\overline{WE}$ ,  $\overline{OE}$ , I/O) can be in the high impedance state.
  - 5. Typical values are at V<sub>CC</sub> = 3.0 V, Ta = +25°C and specified loading, and not guaranteed.
  - 6. t<sub>RC</sub> = read cycle time.

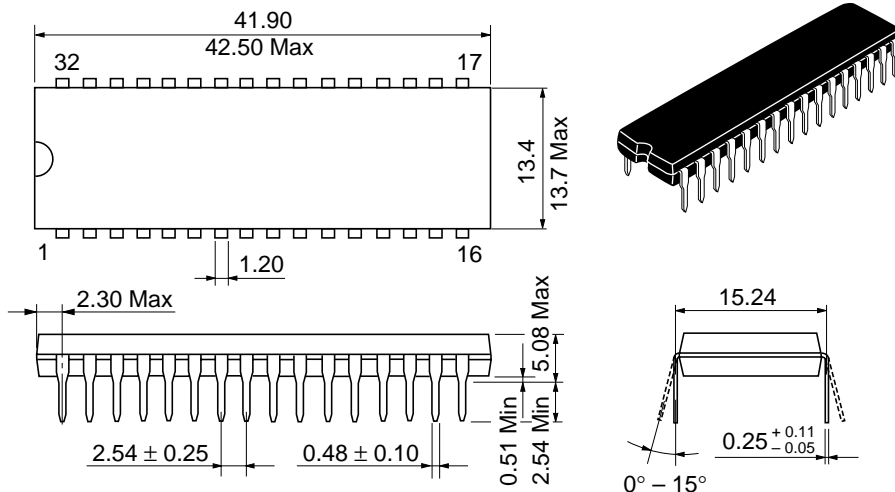
Low V<sub>CC</sub> Data Retention Timing Waveform ( $\overline{CS}$  Controlled)



# Package Dimensions

## HM628512BLP Series (DP-32)

Unit: mm

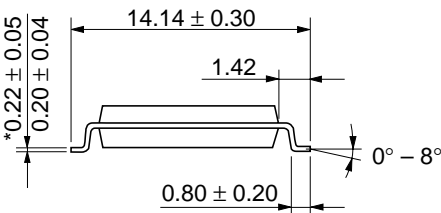
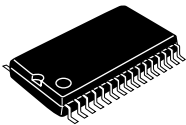
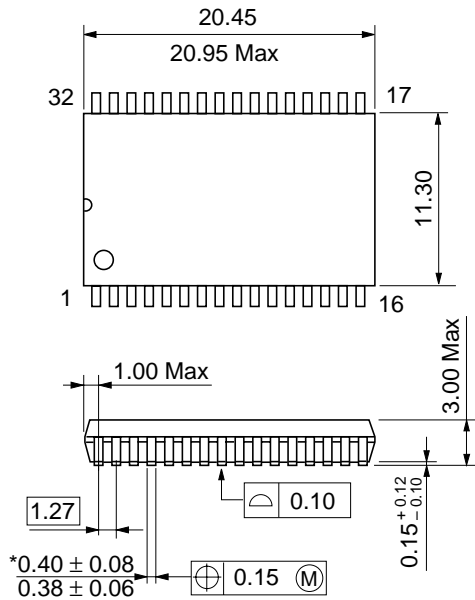


Hitachi Code	DP-32
JEDEC	—
EIAJ	Conforms
Weight (reference value)	5.1 g

Package Dimensions (cont.)

HM628512BLFP Series (FP-32D)

Unit: mm



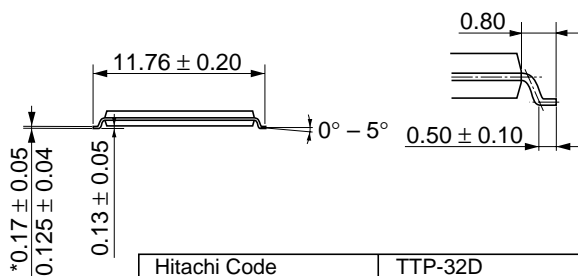
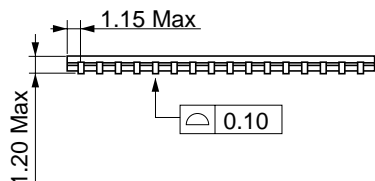
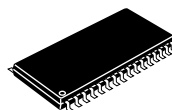
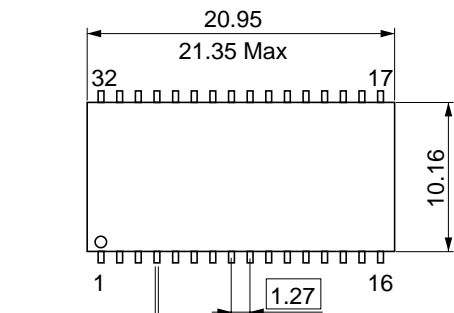
\*Dimension including the plating thickness  
Base material dimension

Hitachi Code	FP-32D
JEDEC	Conforms
EIAJ	—
Weight (reference value)	1.3 g

Package Dimensions (cont.)

HM628512BLTT Series (TTP-32D)

Unit: mm



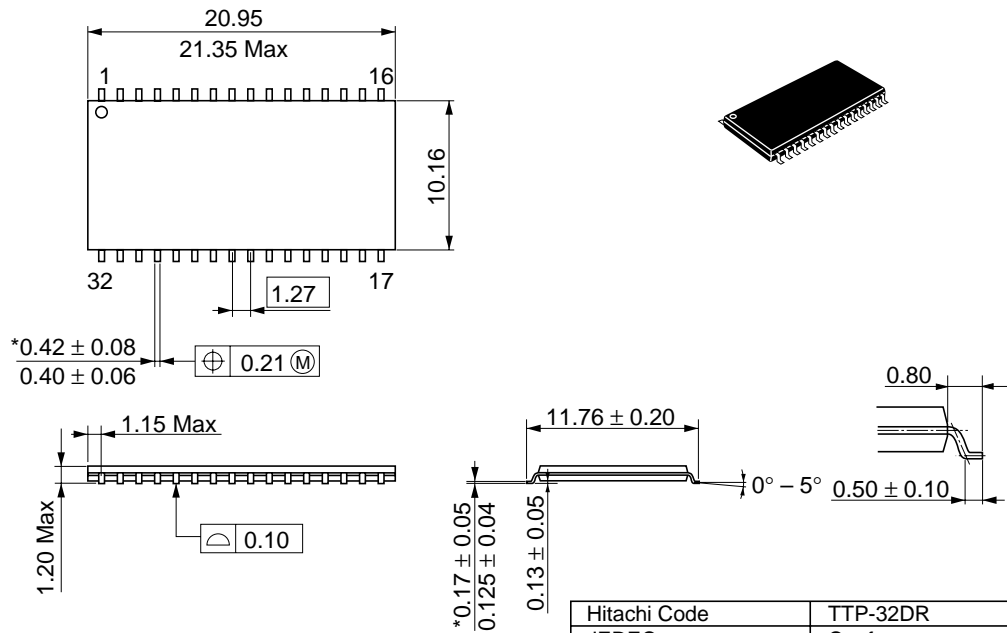
\*Dimension including the plating thickness  
Base material dimension

Hitachi Code	TTP-32D
JEDEC	Conforms
EIAJ	—
Weight (reference value)	0.51 g

Package Dimensions (cont.)

HM628512BLRR Series (TTP-32DR)

Unit: mm



\*Dimension including the plating thickness  
Base material dimension

Hitachi Code	TTP-32DR
JEDEC	Conforms
EIAJ	—
Weight (reference value)	0.51 g



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## Revision Record

Rev.	Date	Contents of Modification	Drawn by	Approved by
0.0	Apr. 24, 1998	Initial issue	M. Higuchi	K. Imato
0.1	Nov. 19, 1998	DC Characteristics $I_{SB1}$ max: 40/20 $\mu$ A to 100/50 $\mu$ A Low $V_{CC}$ Data Retention Characteristics $I_{CCDR}$ max: 20/10 $\mu$ A to 50/15 $\mu$ A Change of note1 and 2	S. kunito	K. Imato
1.0	Jan. 13, 1999	Deletion of Preliminary Features Change of Power dissipation Standby: TBD (typ) to 10 $\mu$ W (typ) DC Characteristics $I_{SB1}$ typ: TBD/TBD to 2/2 $\mu$ A Low $V_{CC}$ Data Retention Characteristics $I_{CCDR}$ typ: TBD/TBD to 1/1 $\mu$ A	S. kunito	K. Imato
2.0	Apr. 8, 1999	Addition of L-UL-version DC Characteristics $I_{SB1}$ typ: 2/2 $\mu$ A to 2/2/2 $\mu$ A $I_{SB1}$ max: 100/50 $\mu$ A to 100/50/20 $\mu$ A Addition of note4 Low $V_{CC}$ Data Retention Characteristics $I_{CCDR}$ typ: 1/1 $\mu$ A to 1/1/1 $\mu$ A $I_{CCDR}$ max: 50/15 $\mu$ A to 50/15/10 $\mu$ A Addition of note3	S. kunito	K. Makuta
3.0	Aug. 24, 1999	Low $V_{CC}$ Data Retention Characteristics Correct error: $t_R$ unit ms to ns		

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